

ABSTRACT

PROCESS FOR ELECTROPLATING NONCONDUCTIVE SURFACE

The invention relates to a process for directly electroplating a conductive metal to the inner walls of through-holes in printed-wiring boards. The process comprises steps of providing an aqueous dispersion containing graphite with an average particle diameter of 2 μm or less and a binder; applying said aqueous dispersion of graphite particles over a surface of a substrate with conductive metal layers laminated over the surface thereof and through-holes provided therethrough, to attach graphite particles, thus forming a graphite layer; removing the graphite layer attached to the surface of the conductive metal layers by etching these metal layers for a thickness of 0.01 to 1.8 μm ; and electroplating using the graphite layer as a conductive layer.

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